

# Automotive Power Management IC PMIC for Automotive Camera

## BD868xxMUF-C Series

### General Description

The PMIC BD868XXMUF-C series consists of primary DCDC, dual secondary DCDC, secondary liner regulator for CMOS sensor, and image sensing power supply. This IC is optimal for camera module, which requires small board with small package VQFN20FV3535. This IC has the spread spectrum providing a lower noise regulated outputs.

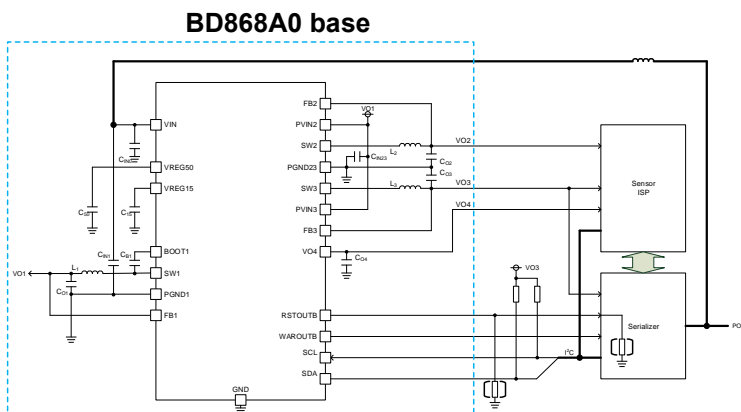
### Features

- AEC-Q100 Qualified (Note 1)
- ISO 26262 Process Compliant to Support ASIL-B
- Primary Buck DCDC Converter (VO1)  
DCDC with Built-in FET  
High Efficiency with Synchronous Rectification
- Dual Secondary Buck DCDC Converter (VO2, VO3)  
DCDC with Built-in FET  
High Efficiency with Synchronous Rectification
- Secondary LDO (VO4)
- Spread Spectrum Frequency Modulation
- Each Protection Function
- BIST at Startup
- 2-wire Interface communication (I<sup>2</sup>C protocol)
- GPO terminal for heater driver (BD868B0 base only)  
(Note 1) Grade 1

### Applications

- ADAS
- Camera System Using CMOS Sensor

### Typical Application Circuit



### Key Specifications

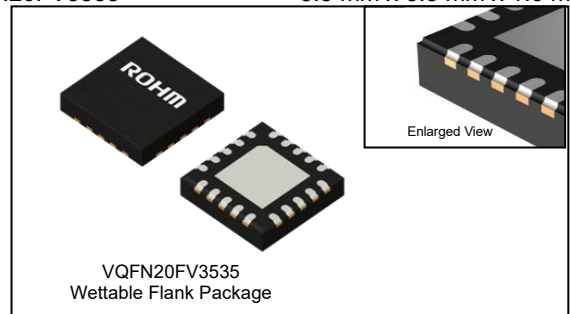
- Input Voltage Rating: 20 V (Max)
- Power Supply Voltage: 4.0 V to 18 V
- Output Voltage (VO1): 3.0-5.0 V (Note2) (±2%)
- Output Voltage (VO2): 0.95-1.5, 1.8 V (Note2) (±2%)
- Output Voltage (VO3): 0.95-1.5, 1.8 V (Note2) (±2%)
- Output Voltage (VO4): 2.7-3.5 V (Note2) (±2%)
- Output Current (IO1): 2 A (Max)
- Output Current (IO2): 1.2 A (Max)
- Output Current (IO3):BD868A0 base 1 A (Max)
- Output Current (IO3):BD868B0 base 0.4 A (Max)
- Output Current (IO4): 0.3 A (Max)
- Switching Frequency: 2.25 MHz (±250 kHz)
- Operating Temperature Range: -40 °C to +125 °C  
(Note 2) Setting available range.

### Package

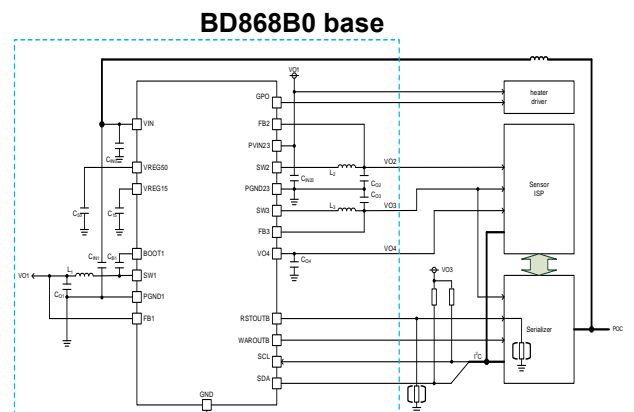
VQFN20FV3535

W (Typ) x D (Typ) x H (Max)

3.5 mm x 3.5 mm x 1.0 mm



VQFN20FV3535  
Wettable Flank Package



## Product Lineups

part No.	Base Part	item	DC/DC			LDO	Function		
			CH1	CH2	CH3	CH4	ISO 26262 supported	Protection	SSCG
☆BD868A0MUF-C	A0	Ouptut voltage (Typ.)	3.7V	1.1V	1.8V	3.3V	✓	✓	✓
		Output current (Max.)	2.0A	1.2A	1.0A	0.3A			
☆BD868B0MUF-C	B0	Ouptut voltage (Typ.)	3.7V	1.1V	1.8V	3.3V	✓	✓	✓
		Output current (Max.)	2.0A	1.2A	0.4A	0.3A			
BD868C0MUF-C	A0	Ouptut voltage (Typ.)	3.3V	1.2V	1.8V	2.8V	✓	✓	✓
		Output current (Max.)	2.0A	1.2A	1.0A	0.3A			
☆BD868C1MUF-C	A0	Ouptut voltage (Typ.)	3.8V	1.1V	1.8V	3.3V	-	✓	✓
		Output current (Max.)	2.0A	1.2A	1.0A	0.3A			
BD868D0MUF-C	A0	Ouptut voltage (Typ.)	3.3V	1.2V	1.8V	2.8V	✓	✓	✓
		Output current (Max.)	2.0A	1.2A	1.0A	0.3A			

\*C0 and D0 have the same output voltage but different sequence control.

☆In development



<ComfySIL™ brand>

ROHM has launched the [ComfySIL™](#) brand for its stakeholders, including customers who design functional safety, so that its products can contribute to the safety, security, and comfort of social systems.

This, [ComfySIL™](#), is awarded to products that follow the [ComfySIL™](#) philosophy for functional safety, not only in the automotive field but also in the industrial equipment field.

ComfySIL™ Web site:

<https://www.rohm.co.jp/functional-safety>

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## Operational Notes

## 1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

## 2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

## 3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

## 4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

#### 5. Recommended Operating Conditions

The function and operation of the IC are guaranteed within the range specified by the recommended operating conditions. The characteristic values are guaranteed only under the conditions of each item specified by the electrical characteristics.

#### 6. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

#### 7. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

#### 8. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

#### 9. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. Unless otherwise specified, unused input pins should be connected to the power supply or ground line.

Operational Notes – continued

10. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When  $GND > Pin A$  and  $GND > Pin B$ , the P-N junction operates as a parasitic diode.

When  $GND > Pin B$ , the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

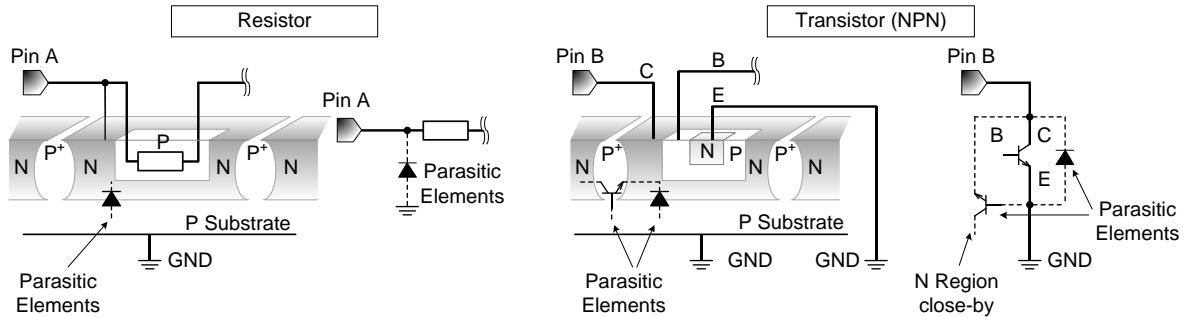


Figure. Example of monolithic IC structure

11. Ceramic Capacitor

When using a ceramic capacitor, determine a capacitance value considering the change of capacitance with temperature and the decrease in nominal capacitance due to DC bias and others.

12. Thermal Shutdown Circuit (TSD)

This IC has a built-in thermal shutdown circuit that prevents heat damage to the IC. Normal operation should always be within the IC's maximum junction temperature rating. However the rating is exceeded for a continued period, the junction temperature ( $T_j$ ) will rise which will activate the TSD circuit that will turn OFF power output pins. When the  $T_j$  falls below the TSD threshold, the circuits are automatically restored to normal operation.

Note that the TSD circuit operates in a situation that exceeds the absolute maximum ratings and therefore, under no circumstances, should the TSD circuit be used in a set design or for any purpose other than protecting the IC from heat damage.

13. Over Current Protection Circuit (OCP)

This IC incorporates an integrated overcurrent protection circuit that is activated when the load is shorted. This protection circuit is effective in preventing damage due to sudden and unexpected incidents. However, the IC should not be used in applications characterized by continuous operation or transitioning of the protection circuit.

14. Functional Safety

“ISO 26262 Process Compliant to Support ASIL-\*\*\*”

A product that has been developed based on an ISO 26262 design process compliant to the ASIL level described in the datasheet.

“Safety Mechanism is Implemented to Support Functional Safety (ASIL-\*\*\*)”

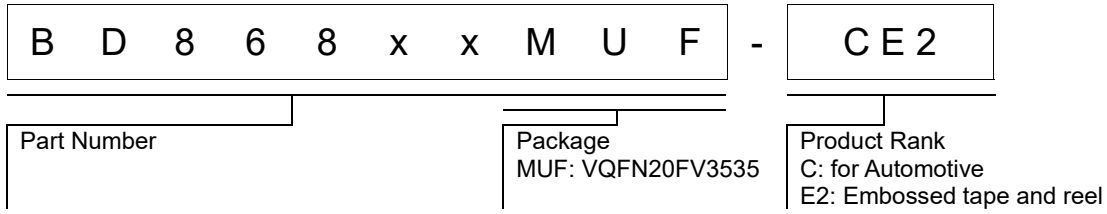
A product that has implemented safety mechanism to meet ASIL level requirements described in the datasheet.

“Functional Safety Supportive Automotive Products”

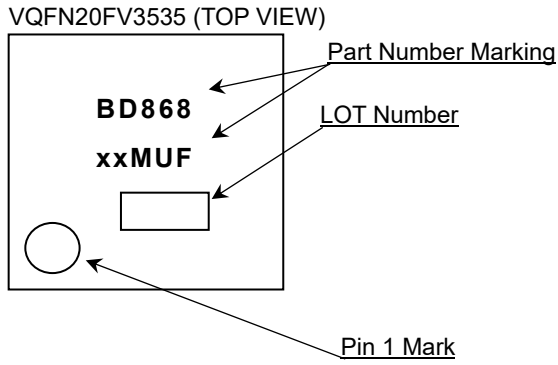
A product that has been developed for automotive use and is capable of supporting safety analysis with regard to the functional safety.

Note: “ASIL-\*\*\*” is stands for the ratings of “ASIL-A”, “-B”, “-C” or “-D” specified by each product's datasheet.

Ordering Information

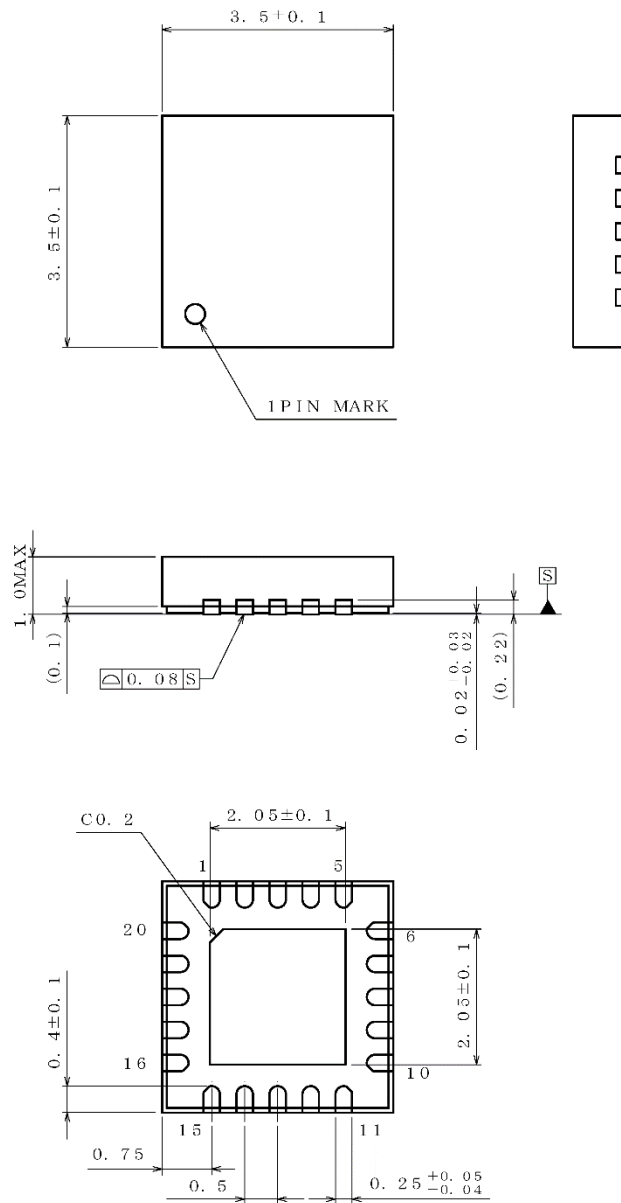


Marking Diagrams



Physical Dimension and Packing Information

Package Name VQFN20FV3535

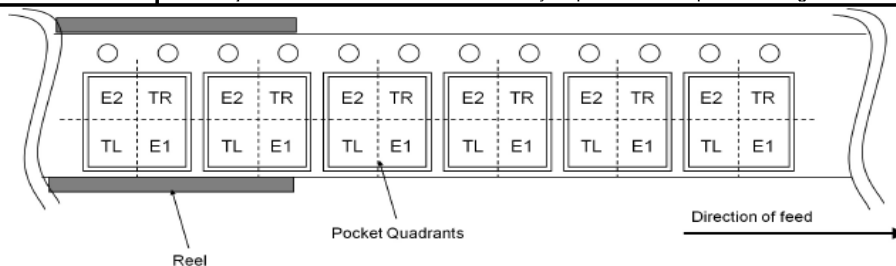


(UNIT: mm)  
 PKG: VQFN20FV3535  
 Drawing No. EX375-5001-4

NOTE: Dimensions in ( ) for reference only.

< Tape and Reel Information >

Tape	Embossed carrier tape
Quantity	2500pcs
Direction of feed	E2 The direction is the pin 1 of product is at the upper left when you hold reel on the left hand and you pull out the tape on the right hand



Revision History

Date	Revision	Changes
06. Apr. 2022	001	New Release

# Notice

## Precaution on using ROHM Products

1. If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment <sup>(Note 1)</sup>, aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
  - [a] Installation of protection circuits or other protective devices to improve system safety
  - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
3. Our Products are not designed under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc. prior to use, must be necessary:
  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
4. The Products are not subject to radiation-proof design.
5. Please verify and confirm characteristics of the final or mounted products in using the Products.
6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
8. Confirm that operation temperature is within the specified range described in the product specification.
9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

## Precaution for Mounting / Circuit board design

1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification



**Precautions Regarding Application Examples and External Circuits**

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

**Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

**Precaution for Storage / Transportation**

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

**Precaution for Product Label**

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

**Precaution for Disposition**

When disposing Products please dispose them properly using an authorized industry waste company.

**Precaution for Foreign Exchange and Foreign Trade act**

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